

SPECIFICATION

MATERIAL

Insulator: Thermal Plastic UL94V-0

Contacts: Copper Alloy

Boardlock: Copper Alloy

CONTACT PLATING

Underplated: 50m Nickel

Contact Area: 1m~30m Selective Gold

Solder Tails Area: 100m Tin/Lead(Brighten Tin) or

100m Tin/Lead Free(Brighten Tin/Matte Tin)

ELECTRICAL

Current Rating: 1 Amps Max.

Contact Resistance: 100 mohms Max.

Insulation Resistance: 1000 Mohms Min.

MECHANICAL

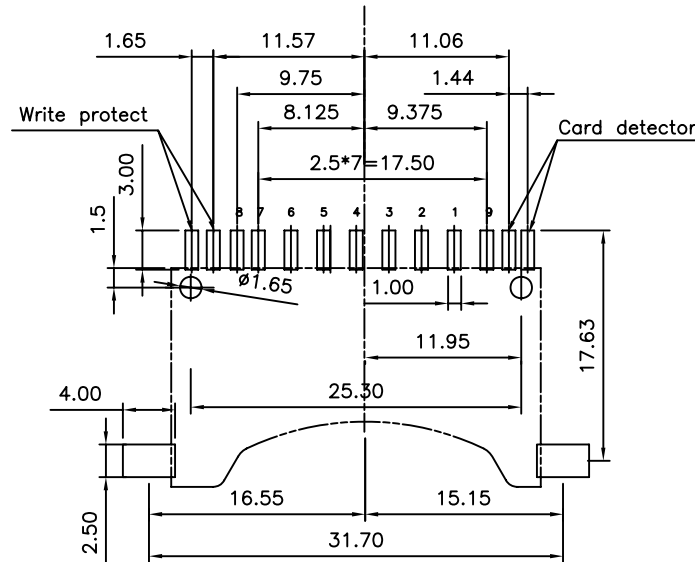
Mating Cycle: 5000 Cycles Minute

Operating temperature: -40°C To +85°C

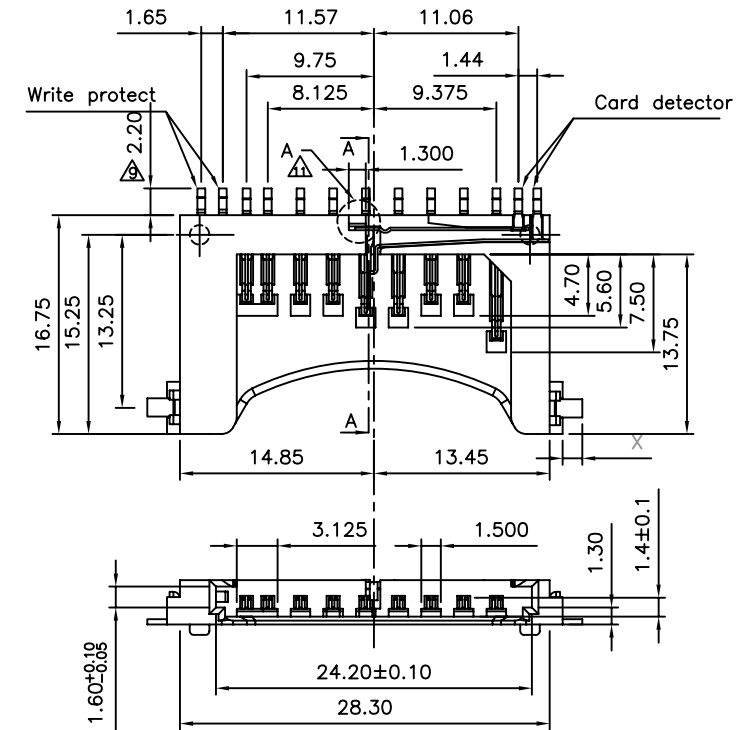
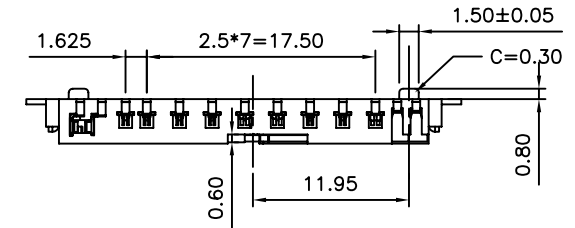
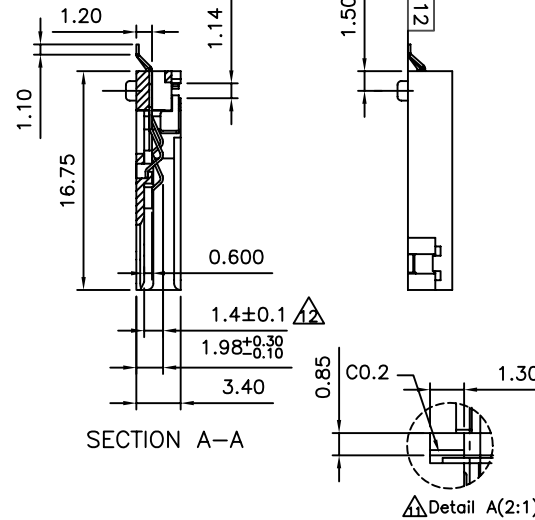
SDC-W25XB-09-LF

LEADFREE

RoHS Compliant



RECOMMENDED P.C.B LAYOUT
TOLERANCES: $\pm 0.05\text{mm}$



PART NO. SDC-W25XB-09

DWG NO. SDC-W25XB-09

FILE NO.

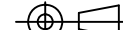
UNIT / mm

SCALE 1:1

CHECKED BY CY

DRAWING BY

PROJECTION



TOLERANCES ARE

.X ± 0.2

.XX $\pm$

.XXX $\pm$

AWG

DESCRIPTION:

MEMORY CARD
SECURE DIGITAL (STANDARD)

AREA

REVISIONS

HK

DATE